





AGH UNIVERSITY OF SCIENCE AND TECHNOLOGY

## Compact forward calorimetry at future linear collider

Marek Idzik AGH-UST

On behalf of FCAL Collaboration

Energy and time measurement with High Granularity Silicon Devices , DESY 13-14 June 2016



- Motivation&Status
- Prototype of Very Compact Calorimeter next FCAL Goal
- Other FCAL R&D
- Summary



## **Motivation for this work**



Development of the very forward region calorimeters for the precise measurement of luminosity (LumiCal) and a fast beam monitoring (BeamCal) in future Linear Collider, with specific requirements/challenges:

- Compact (small Moliere radius)
- Fast readout
- High occupancy
- Rad-hard (BeamCal~1MGy/year)
- Mechanical precision (LumiCal)
- Coverage extension

## Motivation AGH Forward detectors to build: LumiCal, BeamCal

#### LumiCal





- Sandwich type sampling calorimeters
  - LumiCal Si-W,
  - BeamCal GaAs(?)-W
- 30 layers at ILC, 40 layers at CLIC. One W layer 1 X0
- Very compact calorimeters (Moliere radius ~1cm)
- Low polar angle acceptance
  - LumiCal ~100 mrad
  - BeamCal ~10 mrad

#### BeamCal



- compensated GaAs sensors
- 500 um thick
- uniform segmentation

- standard *p* in *n* Si sensors
- 300 um thick, pad pitch 1.8 mm
- Azimuthal/radial segmentation 48 sectors / 64 pads



### Forward detectors Status&Goal Prototype of Compact calorimeter

## Present Status

- Existing LumiCal/BeamCal prototype comprises:
- Detector modules:
  - Sensor modules for BeamCal/LumiCal
  - Readout ASICs
  - Back-end electronics
- Precise absorber layers
- Precise mechanical frame -

## The goal is to make it very compact

- To verify MC simulations
- To proof the used technologies





## Next FCAL goal Precise mechanical frame and absorber plates

AGH



**Precise mechanical frame** 

- can hold up to 30 sensorabsorber layers
- Various configurations of detector modules and absorber plates are possible



Prototype tungsten plates

• 3.5 mm thick (1X0)

 Required flatness on front/back side -10/50um

• 11 prototype plates from two companies. Four of them fulfill flatness specifications

Existing mechanical frame and tungsten plates were already used in testbeams and match the requests for compact prototype



## Next FCAL goal New detector module

For very compact calorimeter (Moliere radius ~1cm) the existing detector module (sensor+readout) is much too thick (>1cm) and needs to be miniaturisied:

- A very thin (<1 mm) **new sensor module is needed** 
  - using existing silicon sensors
- A thin (<4.5 mm) **new readout board** with SystemOnChip (SoC) type ultra-low power readout ASICs
  - New readout ASICs needed
  - New FPGA based readout needed





Project of new sensor module



For the envelope 3D printing and and carbon fiber prototypes were done. Carbon fiber prototypes were chosen as more rigid.



# New sensor module H Low-height contact of the sensor

- Approaches :
  - wirebonding

conventional, currently used, minimum height ~100µm

Flat loop wire bonding

staggered pcb required

Conductive glue

tested at DESY, Krakow, TAU : not satisfying ...

• Laser bonding

tested by TAU : not possible because aluminum pads

tape automated bonding (TAB)

first enquiries by TAU

bonding wedge & dedicated fanout sample received

- Spring loaded contact
  - technology tests by DESY (Zeuthen)















Thin prototypes of sensor modules comprising the envelope, fanouts and sensor have been developed and put on beam at the end of 2015. Data analyses in progress...



New study ongoing with Hamamatsu to limit dead area at the edges between tiles (each tile has 4 sectors)





## New readout ASIC FLAME – FcaL Asic for Multiplane rEadout

- For very compact calorimeter we need an ultra-low power, SoC type (all functionalities on chip) readout ASIC
- FLAME: 16-channel ultra-low power readout ASIC in CMOS 130 nm, FE&ADC in ech channel, fast serialization and data transmission, all functionalities in single ASIC



## New readout ASIC Channel architecture



- Analogue front-end comprises:
  - Charge sensitive preamplifier with variable gain
    - High gain MIP sensitivity for calibration
    - Low gain for shower development (up to 6 pC)
  - Differential CR-RC shaper with 50ns peaking time
  - Cdet 5-50 pF

AGH

Power ~1.2mW

- 10-bit ADC
  - Sampling rate up to 40 MSps
  - DNL, INL < 0.75 LSB
  - ENOB > 9
  - Ultra-low power <1mW@40Msps</li>



## New readout ASIC FLAME current status

- Prototype ASIC comprising 8 almost fully functional FLAME channels:
  - Front-end with variable gain, differential CR-RC shaper, Tpeak = 50ns, ENC~900el@20pF
  - 10-bit multichannel SAR ADC

setups under preparation...

Power (FE+ADC) <2mW/channel



- Fast ultra-low power multi-phase PLL
- Power <20mW@10Gbps
- Fast serializer  $22b \rightarrow 1b$
- Fast SST driver



## Other FCAL R&Ds Radiation studies of BeamCal sensors at SLAC

Studies done in realistic radiation field, as expected for ILC/CLIC

Sensor Type	Notable Exposures (Mrad)
GaAs	20
SiC	80
Si PF	<mark>270</mark> , 570
Si NF	300
Si PC	300
Si NC	290

Promising results with Si (although cooling would probably be required...)

#### P-type Float Zone Si Charge Collection after 2.7MGy=270Mrad



@600 V, ~20% charge collection loss (60C annealing)



#### Other FCAL R&Ds New BeamCal design with sapphire sensors

Motivation: extreme radiation hardness of sapphire, reduced dynamic range of the front-end electronics





- Dedicated R&D is ongoing for forward calorimetery at future linear collider. Prototype of very compact calorimeter FCAL next goal is in advanced stage:
  - Precise mechanical frame and tungsten plates have been developed
  - Prototypes of **new** thin sensor modules are just being completed
  - Prototypes of **new** fast, ultra-low power SoC type readout ASIC will be tested soon,
  - In parallel various R&Ds, like studies of new radhard sensors for BeamCal, are underway.

# Thank you for attention





#### Shower development from 2014 test-beam



Measured shower development for 5 GeV electrons shows good agreement with MC simulations



#### **Forward detectors**



## **FCAL overview** AGH Luminosity measurement by LumiCal detector



- Precise measurement of luminosity (10<sup>-3</sup> at ILC, 10<sup>-2</sup> at CLIC)
- Low angle physics

Gauge process for the luminosity measurement: Bhabha scattering

e+e- —> e+e- (γ)

$$\frac{d\sigma_{\rm B}}{d\theta} = \frac{2\pi\alpha_{\rm em}^2}{s} \frac{\sin\theta}{\sin^4(\theta/2)} \approx \frac{32\pi\alpha_{\rm em}^2}{s} \frac{1}{\theta^3}$$





#### **BeamCal sensor material propoertioiies**

	S	Sapphire	Diamond	GaAs	Si	
•	Density, g/cm3	3.98	3.52	5.32	2.33	
•	Dielectric constant	9.3 - 11.5	5.7	10.9	11.7	
•	Breakdown field, V/cm	~106 *	107	4.105		3.105
•	Resistivity, $\Omega$ ·cm	>1014	>1011	107	105	
•	Band gap, eV	9.9	5.45	1.42	1.12	
•	El. mobility, cm2/(V·s)	<b>≻600 **</b>	1800	~8500	1360	
•	Hole mobility, cm2/(V·s)	-	1200	-	460	
•	MIP eh pairs created, eh/µn	n 22	36	150	73	

#### +First irradiation tests of SiC

- \* Typical operation field ~1-2.104 V cm-1
- \*\* at 20°C, ~30000 at 40°K



## **GaAs radiation studies**



## Ongoing FCAL R&D on ASICs AGH Readout ASICs for BeamCal in CMOS 180 nm



- Novel front-end architecture based on switched-capacitor filter
- Front-end and 10-bit ADC in each channel (as in LumiCal readout)
- Adder circuit for fast beam diagnostics
- First single channel prototypes fabricated and tested
- Development of next ASIC version in progress at PUC Chile

A. Abusleme, A. Dragone, G. Haller, B. Wooley "BeamCal Instrumentation IC: Design, Implementation and Test Results", IEEE Transactions on Nuclear Science, 59(3) 2012